

PROFET™ Wire Guard 12V - Daughterboard description

User guide

About this document

Scope and purpose

This document explains the latest evaluation boards for the PROFET™ Wire Guard 12V family. It focuses on the *daughterboard (DB)*, which is part of a kit which includes a *motherboard (MB)*. The DB requires a MB to function, as they are not functional as standalone components. For information on the MB, visit the company website.

Intended audience

This user guide is intended for automotive electronics engineers, designers, and technicians who are responsible for the development, testing, and implementation of high side switch solutions using the PROFET™ Wire Guard 12 V family of devices. The target audience includes individuals who require a detailed understanding of the DB's features, functionality, and operation, as well as those who need to integrate the device into their automotive systems. This document is also relevant for application engineers, system designers, and quality assurance personnel who are involved in the development and validation of automotive ECUs that utilize high side switch technology. Additionally, the guide may be useful for students and researchers in the field of automotive electronics who are interested in learning about the application and implementation of high side switch devices in automotive systems. The intended audience is assumed to have a basic understanding of automotive electronics, electrical engineering principles, and microcontroller-based systems.

About this product group

Target applications

- Headlight control modules
- Fuel pump control
- Horn and accessory control
- Battery management systems
- Heated seat and window control
- Trailer and tow control
- Body control modules

Product family

PROFET™ Wire Guard 12V

Note: *printed circuit board (PCB) and auxiliary circuits are not optimized for final customer designs.*

Safety precautions

Safety precautions

Note: Note the following warnings regarding the hazards associated with development systems.

Table 1 Safety precautions

	<p>Warning: The DC-link potential of this board is up to 1000 VDC. When measuring voltage waveforms by oscilloscope, high voltage differential probes must be used. Failure to do so may result in personal injury or death.</p>
	<p>Warning: The evaluation or reference board contains DC bus capacitors which take time to discharge after removal of the main supply. Before working on the drive system, wait five minutes for capacitors to discharge to safe voltage levels. Darkened display LEDs are not an indication that capacitors have discharged to safe voltage levels.</p>
	<p>Warning: The evaluation or reference board is connected to the grid input during testing. Hence, high-voltage differential probes must be used when measuring voltage waveforms by oscilloscope. Failure to do so may result in personal injury or death. Darkened display LEDs are not an indication that capacitors have discharged to safe voltage levels.</p>
	<p>Warning: Remove or disconnect power from the drive before you disconnect or reconnect wires, or perform maintenance work. Wait five minutes after removing power to discharge the bus capacitors. Do not attempt to service the drive until the bus capacitors have discharged to zero. Failure to do so may result in personal injury or death.</p>
	<p>Caution: The heat sink and device surfaces of the evaluation or reference board may become hot during testing. Hence, necessary precautions are required while handling the board. Failure to comply may cause injury.</p>
	<p>Caution: Only personnel familiar with the drive, power electronics and associated machinery should plan, install, commission and subsequently service the system. Failure to comply may result in personal injury and/or equipment damage.</p>
	<p>Caution: The evaluation or reference board contains parts and assemblies sensitive to electrostatic discharge (ESD). Electrostatic control precautions are required when installing, testing, servicing or repairing the assembly. Component damage may result if ESD control procedures are not followed. If you are not familiar with electrostatic control procedures, refer to the applicable ESD protection handbooks and guidelines.</p>
	<p>Caution: A drive that is incorrectly applied or installed can lead to component damage or reduction in product lifetime. Wiring or application errors such as undersizing the motor, supplying an incorrect or inadequate AC supply, or excessive ambient temperatures may result in system malfunction.</p>
	<p>Caution: The evaluation or reference board is shipped with packing materials that need to be removed prior to installation. Failure to remove all packing materials that are unnecessary for system installation may result in overheating or abnormal operating conditions.</p>

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1 General information

1 General information

The smart power switches (SPS) evaluation kit consists of a *MB* and a *DB*. Depending on the device's features, the DB provides additional functionalities. It is essential to note that the setup and operation of the DB are contingent upon its combination with a MB. The two components are designed to work in tandem, and the DB's functionality is optimized when used with a motherboard. For users requiring information regarding the MB, including its specifications, setup, and operation, Infineon recommends consulting the relevant documentation available on the homepage. This will provide a more comprehensive understanding of the entire evaluation kit and its capabilities.

The usage of a ground resistor RGND is recommended. Therefore, it is suggested to close the jumper XGND. Depending on which DB is plugged onto the MB, a different number of banana jacks OUT0 to OUT7 are in use. For the best current capability, it is recommended to use the maximum available banana jacks. This is described in each DB chapter.

Note: *Usually in the device's datasheet it is recommended to use an RIS of 1.2 kΩ. This refers to a 5 V logic system. Since the MB and the *microcontroller* provide a 3.3 V logic system, the resistor value RIS was reduced accordingly.*

2 Daughterboard

2 Daughterboard

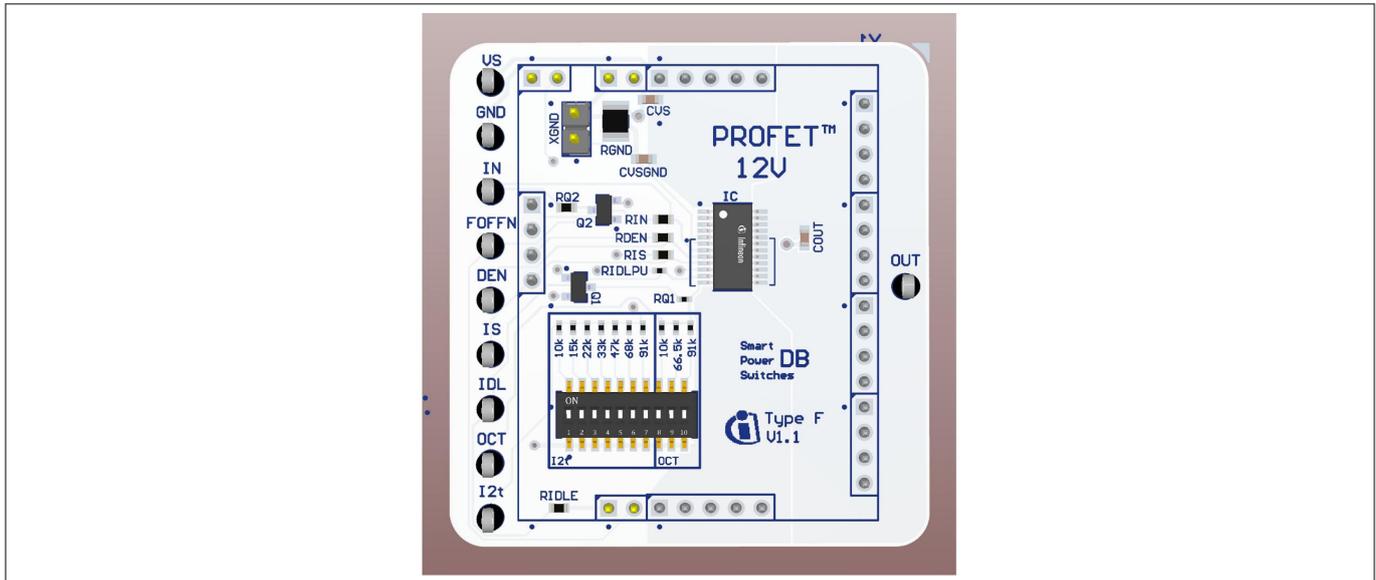


Figure 1 Daughterboard

Because of the pin-to-pin compatibility the *DB* can handle 1-channel PG-TSDSO-14 (for example: BTG7007A-1EPW) and PG-TSDSO-24 (for example: BTG70020A-1ESW). This DB is only able to handle one-channel devices. The correct position of a 14-pin device is indicated by the blue lines on both sides of the footprint, and the dot marking the *ground (GND)* pin position. The correct position of the 24-pin device is marked by the dot in the upper left corner of the footprint for the GND pin.

The OUT current is provided via banana sockets OUT0 – OUT7.

On the DB, there is a dip switch with different values provided for evaluation. The numbering of the resistor values is numbered according to the dip switch from left to right as shown in [Figure 2](#). R1 to R7 are providing a selection of values for the *current squared through time (I²t)* feature. R8 to R10, and RQ1 are reserved for the *overcurrent threshold (OCT)* feature. It is recommended to pick a resistor for both features before using the device. R7 and R8 are not assembled for placing a custom value if needed.

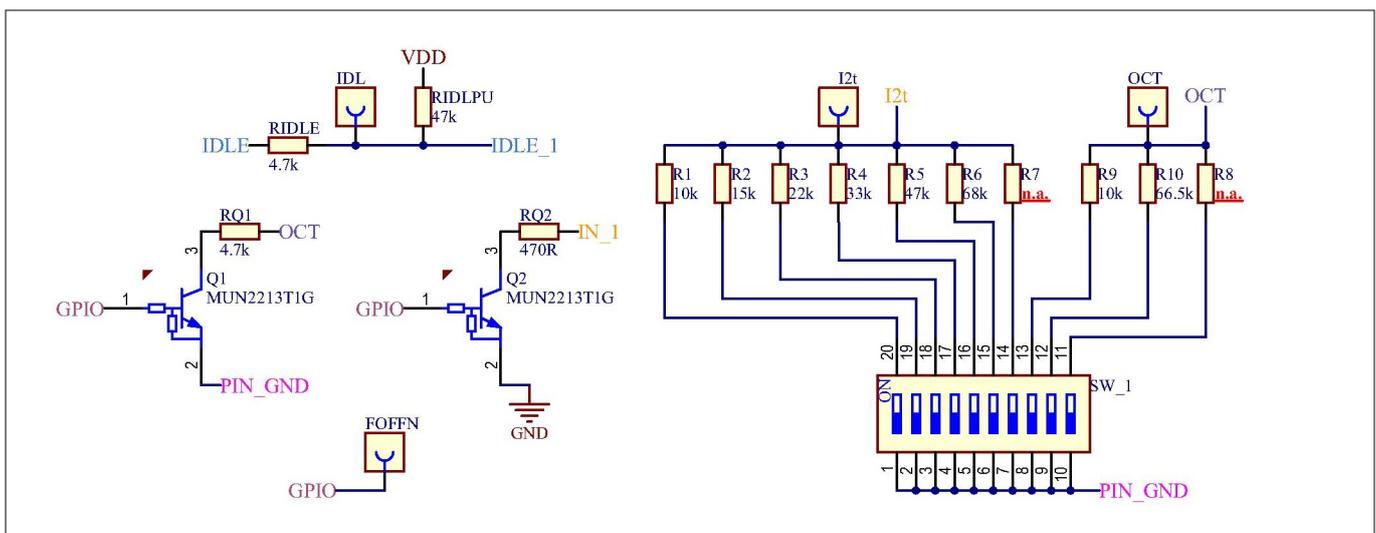


Figure 2 OCT and I2t board design

Resistors RQ1 and RQ2 and transistors Q1 and Q2 are needed for the fast-off feature of the BTG70008A-1ESW. These components come with the DB, if the mentioned device is already mounted. For DBs without this device already mounted, the components as well need to be by soldered manually.

2 Daughterboard

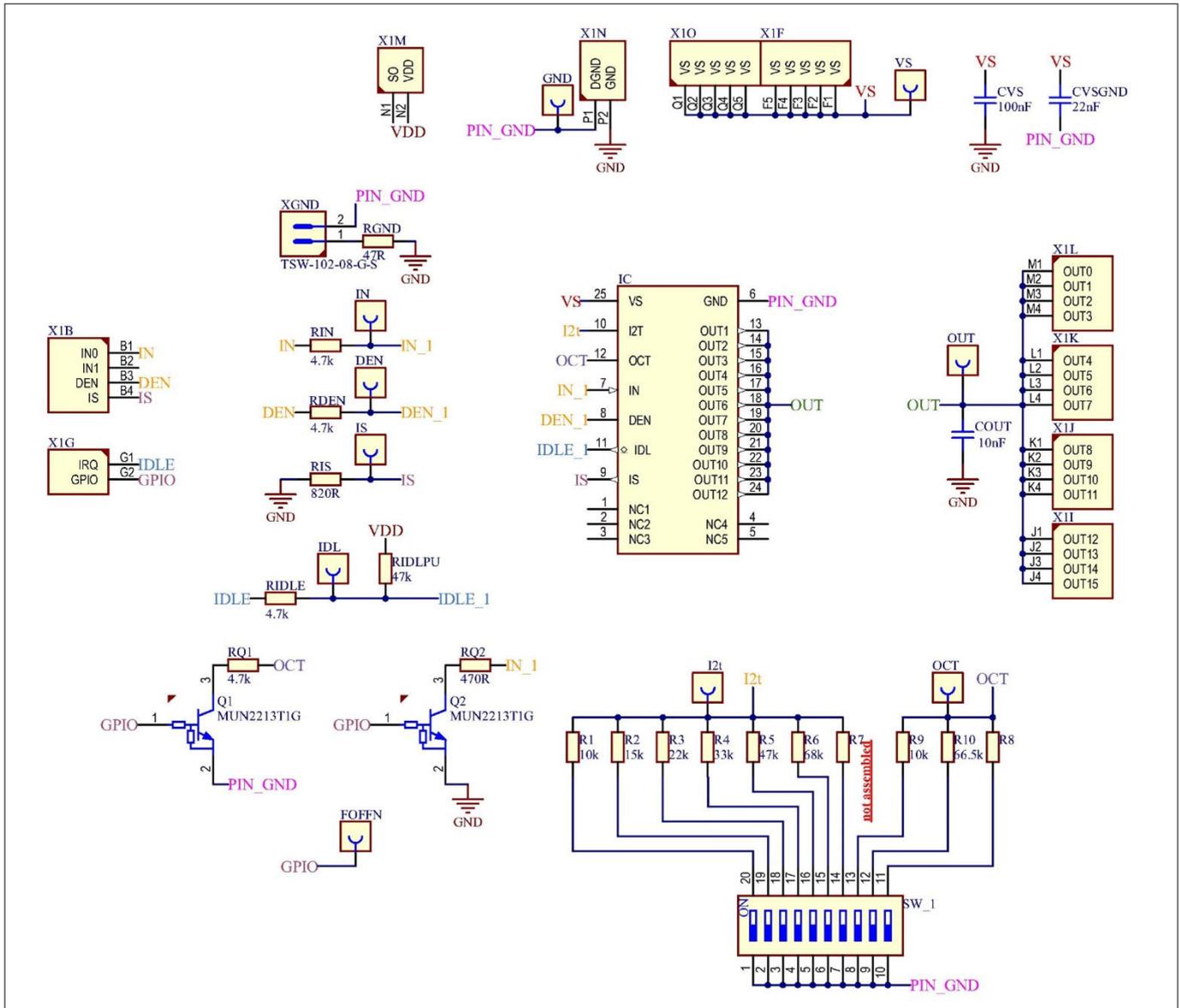


Figure 3 Schematic

Table 2 Product list of compatible devices for this daughterboard

Device name	$I_{L(NOM)}[A]$
BTG70008A-1ESW	36.5
BTG70013A-1ESW	26.6
BTG70020A-1ESW	21.5
BTG7003A-1EPW	15.7
BTG7007A-1EPW	10.3
BTG7016A-1EPW	6.8

3 Bill of materials

3 Bill of materials

Table 3 Bill of materials

Designator	Qty	Fitted	Description
COUT	1	Fitted	CAP/CERA/10 nF/50 V/5%/0603(1608)/SMD
CVS	1	Fitted	CAP/CERA/100 nF/50 V/5%/0603(1608)/SMD
CVSGND	0	No	CAP/CERA/22 nF/50 V/5%/0603(1608)/SMD
DEN, GND, I2t, IN, IS, OCT, OUT, VS	8	Fitted	Black bead terminal assembly 1.02 mm hole
FOFFN, IDL	2	Fitted	Black bead terminal assembly 1.02 mm hole
IC	1	Fitted	PROFET™ Wire Guard smart power high-side switch
Q1, Q2	0	BTG70008A-1E SW only	NPN Transistors, 100m A, 50 V
R1, R9	2	Fitted	RES/STD/10 k/100 mW/1%/0402/SMD
R2	1	Fitted	RES/STD/15 k/63 mW/1%/0402/SMD
R3	1	Fitted	RES/STD/22 k/63 mW/1%/0402/SMD
R4	1	Fitted	RES/STD/33 k/63 mW/1%/0402/SMD
R5, RIDLPU	2	Fitted	RES/STD/47 k/63 mW/1%/0402/SMD
R6	1	Fitted	RES/STD/68 k/63 mW/1%/0402/SMD
R7, R8	0	No	RES/0402/SMD
R10	1	Fitted	RES/STD/66.5 k/63 mW/1%/SMD
RDEN, RIDLE, RIN	3	Fitted	RES/STD/4.7 k/100 mW/1%/0603(1608)/SMD
RGND	1	Fitted	RES/STD/47R/500 mW/1%/1210(3225)/SMD
RIS	1	Fitted	RES/STD/820R/100 mW/1%/0603(1608)/SMD
RQ1	0	BTG70008A-1E SW only	RES/STD/4.7 k/63 mW/1%/0402(1005)/SMD
RQ2	0	BTG70008A-1E SW only	RES/STD/470R/100 mW/1%/0603(1608)/SMD/-
SW_1	1	Fitted	Surface Mount DIP Switches, 97 Series Half-Pitch, 10 Positions
XGND	1	Fitted	Through hole Header, 2.54 mm pitch, 2 pin, vertical, single row

4 Related resources

4 Related resources

- [Product family page](#)
- [What is idle mode in PROFET™ Wire Guard?](#)
- [What is the difference between Sleep and Inactive mode in PROFET™ Wire Guard?](#)
- [Nominal load-current calculation for PROFET™ 12V devices](#)

5 Appendices

5.1 Daughterboards ordering information

Table 4 Daughterboards ordering information

Sales part name	Sales product number
D-BTG70008A-1ESW-1	SP006148206
D-BTG70013A-1ESW-1	SP006142577
D-BTG70020A-1ESW-1	SP006142579
D-BTG7003A-1EPW-1	SP006142581
D-BTG7007A-1EPW-1	SP006142583
D-BTG7016A-1EPW-1	SP006142585
D-PROFET-Wire-Guard-SR-1	SP006136224

5.2 Motherboards ordering information

Table 5 Motherboards ordering information

Board name	Sales part name	Sales product number
SPS Motherboard Lite	M-SMART-POWER-LITE-5	SP006136123
SPS Motherboard	M-SMART-POWER-SWT-5	SP006041408

Revision history

Revision history

Document version	Date of release	Description of changes
Rev 1.00	2025-12-17	Initial release

Glossary

DB

daughterboard (DB)

An expansion circuit card connected to a motherboard.

GND

ground (GND)

I²t

current squared through time (I²t)

An electrical quantity that is used to determine energy to a protective device, such as a circuit breaker or fuse.

MB

motherboard (MB)

The main printed circuit board (PCB) in general-purpose computers and other expandable systems. It holds and allows communication between many of the crucial electronic components of a system, such as the central processing unit (CPU) and memory, and provides connectors for other peripherals.

microcontroller

microcontroller

A small computer on a single integrated circuit containing a processor core, memory, and programmable input/output peripherals.

OCT

overcurrent threshold (OCT)

PCB

printed circuit board (PCB)

A board that mechanically supports and electrically connects electronic components using conductive tracks, pads, and other features etched from copper sheets laminated onto a non-conductive substrate.

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